

SN5476, SN54LS76A
SN7476, SN74LS76A
DUAL J-K FLIP-FLOPS WITH PRESET AND CLEAR
SDS121 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

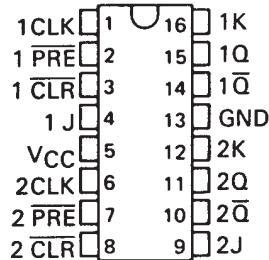
The '76 contains two independent J-K flip-flops with individual J-K, clock, preset, and clear inputs. The '76 is a positive-edge-triggered flip-flop. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS76A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. The preset and clear are asynchronous active low inputs. When low they override the clock and data inputs forcing the outputs to the steady state levels as shown in the function table.

The SN5476 and the SN54LS76A are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7476 and the SN74LS76A are characterized for operation from 0°C to 70°C .

SN5476, SN54LS76A . . . J PACKAGE
SN7476 . . . N PACKAGE
SN74LS76A . . . D OR N PACKAGE

(TOP VIEW)



'76
FUNCTION TABLE

INPUTS					OUTPUTS	
PRE	CLR	CLK	J	K	Q	\bar{Q}
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H [†]	H [†]
H	H	↓	L	L	Q ₀	\bar{Q}_0
H	H	↓	H	L	H	L
H	H	↓	L	H	L	H
H	H	↓	H	H	TOGGLE	

'LS76A
FUNCTION TABLE

INPUTS					OUTPUTS	
PRE	CLR	CLK	J	K	Q	\bar{Q}
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H [†]	H [†]
H	H	↓	L	L	Q ₀	\bar{Q}_0
H	H	↓	H	L	H	L
H	H	↓	L	H	L	H
H	H	↓	H	H	TOGGLE	
H	H	H	X	X	Q ₀	\bar{Q}_0

[†] This configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

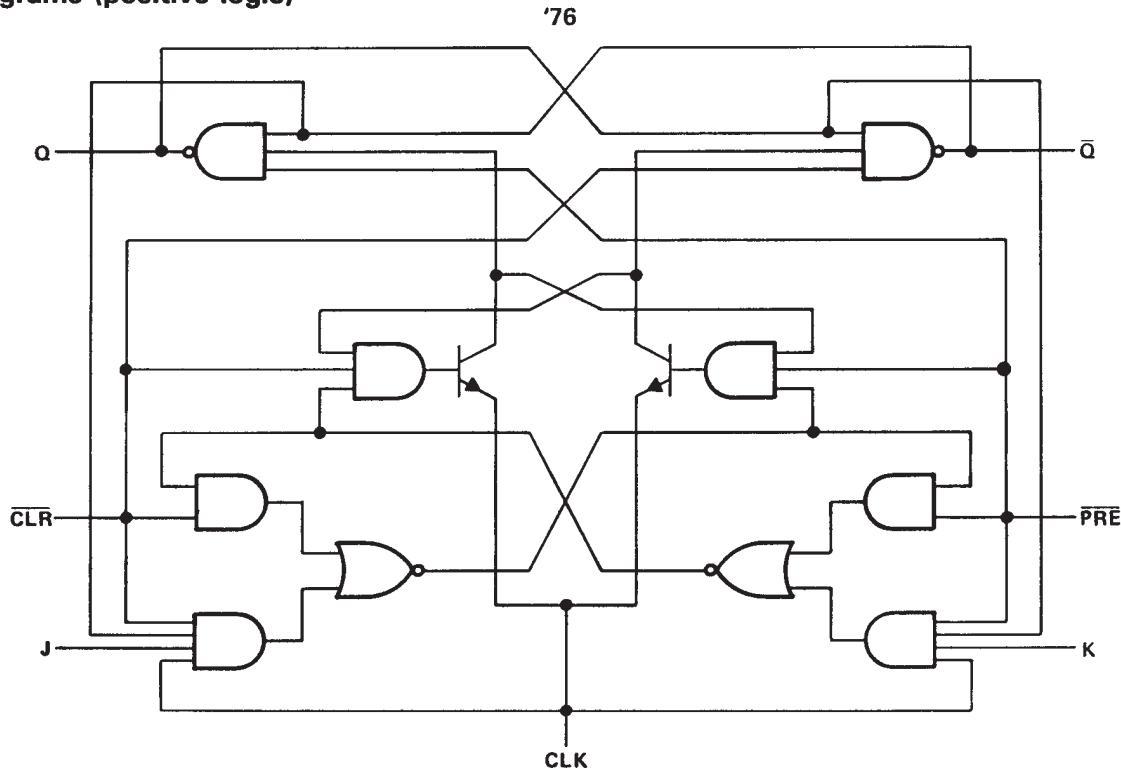
SN5476, SN54LS76A

SN7476, SN74LS76A

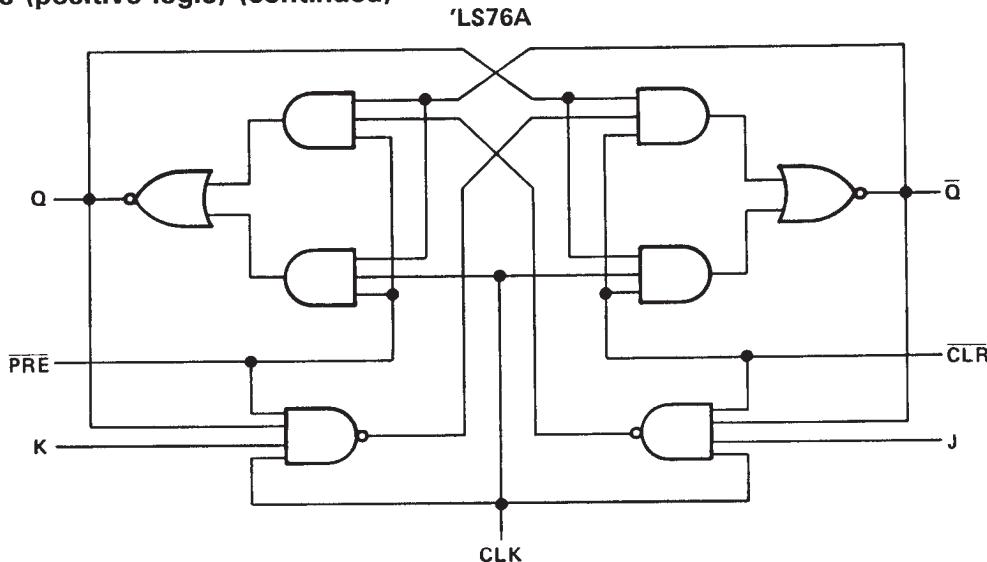
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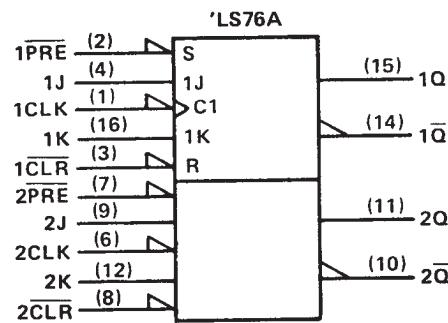
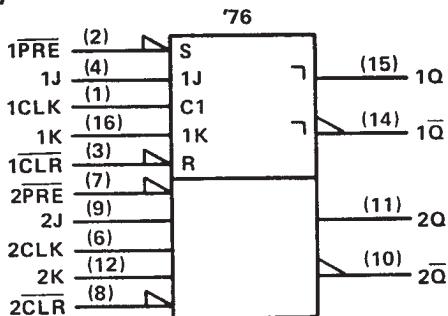
logic diagrams (positive logic)



logic diagrams (positive logic) (continued)

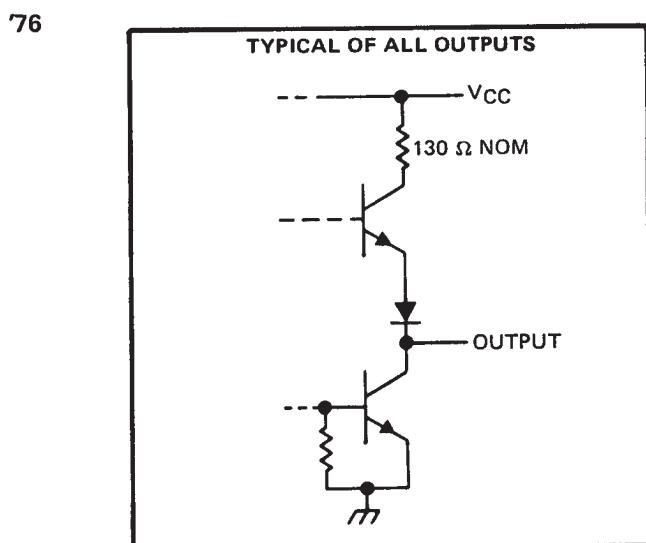
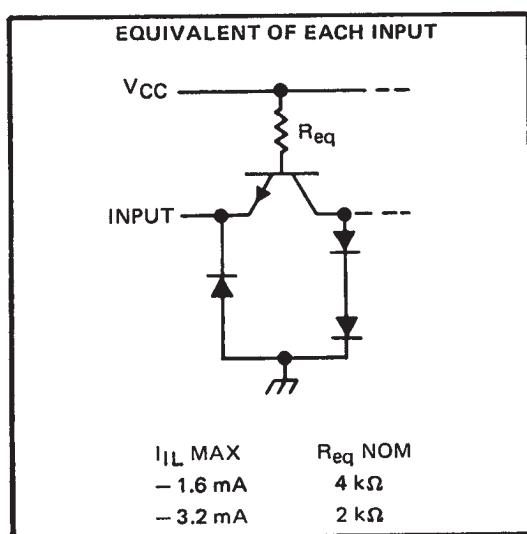


logic symbols[†]



[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

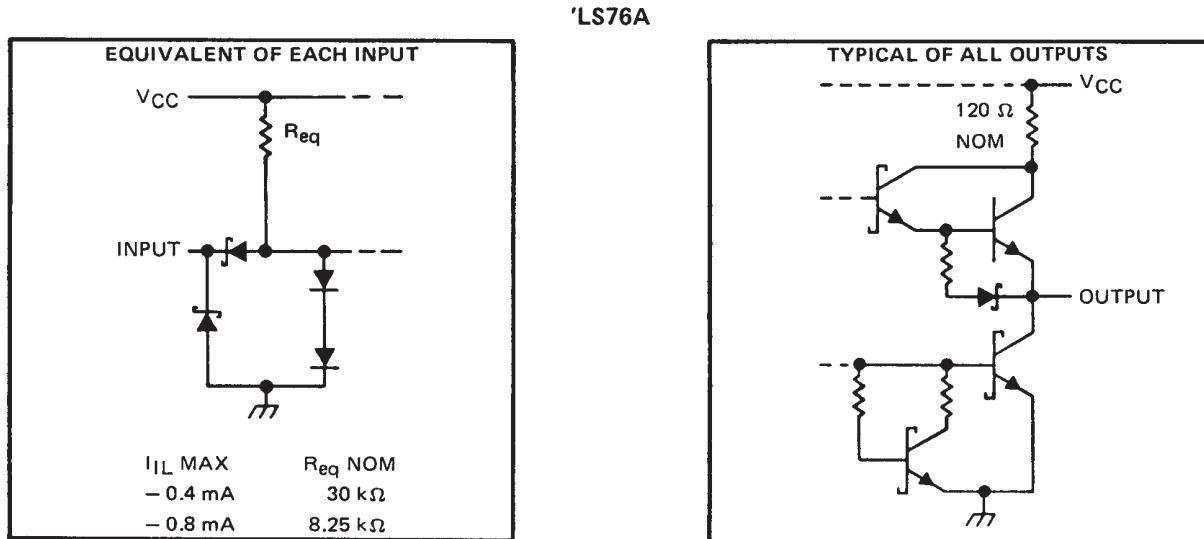
schematics of inputs and outputs



SN5476, SN54LS76A SN7476, SN74LS76A DUAL J-K FLIP-FLOPS WITH PRESET AND CLEAR

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schematics of inputs and outputs (continued)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage: '76	5.5 V
'LS76A	7 V
Operating free-air temperature range: SN54'	-55 °C to 125 °C
SN74'	0 °C to 70 °C
Storage temperature range	-65 °C to 150 °C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5476, SN54LS76A
SN7476, SN74LS76A
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recommended operating conditions

			SN5476			SN7476			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
I _{OH}	High-level output current				–0.4			–0.4	mA
I _{OL}	Low-level output current				16			16	mA
t _W	Pulse duration	CLK high	20			20			ns
		CLK low	47			47			
		PRE or CLR low	25			25			
t _{su}	Input setup time before CLK ↑		0			0			ns
t _h	Input hold time-data after CLK ↓		0			0			ns
T _A	Operating free-air temperature		–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]			SN5476			SN7476			UNIT
				MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{IK}	V _{CC} = MIN, I _I = –12 mA				–1.5			–1.5		V
V _{OH}	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = –0.4 mA			2.4	3.4		2.4	3.4		V
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 16 mA				0.2	0.4		0.2	0.4	V
I _I	V _{CC} = MAX, V _I = 5.5 V					1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V				40			40		μA
					80			80		
I _{IIL}	V _{CC} = MAX, V _I = 0.4 V				–1.6			–1.6		mA
					–3.2			–3.2		
I _{OS} [§]	V _{CC} = MAX			–20	–57	–18	–20	–57		mA
I _{CC} [#]	V _{CC} = MAX, See Note 2			10	20		10	20		mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time.

[¶] Clear is tested with preset high and preset is tested with clear high.

[#] Average per flip-flop.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
f _{max}			R _L = 400 Ω, C _L = 15 pF	15	20		MHz	
t _{PLH}	PRE or CLR	Q or \bar{Q}		16	25		ns	
t _{PHL}				25	40		ns	
t _{PLH}	CLK	Q or \bar{Q}		16	25		ns	
t _{PHL}				25	40		ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN5476, SN54LS76A

SN7476, SN74LS76A

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recommended operating conditions

			SN54LS76A	SN74LS76A	UNIT				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.75	V
V _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.7			0.8	V
I _{OH}	High-level output current				-0.4			-0.4	mA
I _{OL}	Low-level output current				4			8	mA
f _{clock}	Clock frequency		0		30	0		30	MHz
t _W	Pulse duration	CLK high	20			20			ns
		PRE or CLR low	25			25			
t _{su}	Setup time before CLK↓	data high or low	20			20			ns
		CLR inactive	20			20			
		PRE inactive	25			25			
t _h	Hold time-data after CLK↓		0			0			ns
T _A	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN54LS76A			SN74LS76A			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V
V _{OH}	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, I _{OH} = -0.4 mA	2.5	3.4		2.7	3.4		V
V _{OL}	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = 2 V, I _{OL} = 4 mA		0.25	0.4	0.25	0.4		V
	V _{CC} = MIN, V _{IL} = MAX, V _{IH} = 2 V, I _{OL} = 8 mA				0.35	0.5		
I _I	J or K CLR or PRE CLK	V _{CC} = MAX, V _I = 7 V		0.1		0.1		mA
				0.3		0.3		
				0.4		0.4		
I _{IH}	J or K CLR or PRE CLK	V _{CC} = MAX, V _I = 2.7 V		20		20		μA
				60		60		
				80		80		
I _{IL}	J or K All other	V _{CC} = MAX, V _I = 0.4 V		-0.4		-0.4		mA
				-0.8		-0.8		
I _{OS} [§]	V _{CC} = MAX, See Note 4	-20	-100	-20	-100			mA
I _{CC} (Total)	V _{CC} = MAX, See Note 2		4	6	4	6		mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS			MIN	TYP	MAX	UNIT
			R _L = 2 kΩ	C _L = 15 pF					
f _{max}						30	45		MHz
t _{PLH}	PRE, CLR or CLK	Q or \bar{Q}				15	20		ns
t _{PHL}						15	20		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9557501QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-9557501QFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
5962-9557501QFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
7601301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
7601301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/00204BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/00204BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN5476J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN5476J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS76AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS76AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN7476N	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN7476N	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN7476N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN7476N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS76AD	OBsolete	SOIC	D	16		TBD	Call TI	Call TI
SN74LS76AD	OBsolete	SOIC	D	16		TBD	Call TI	Call TI
SN74LS76ADR	OBsolete	SOIC	D	16		TBD	Call TI	Call TI
SN74LS76ADR	OBsolete	SOIC	D	16		TBD	Call TI	Call TI
SN74LS76AN	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS76AN	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS76AN3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74LS76AN3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SNJ5476J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ5476J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ5476W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ5476W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS76AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS76AJ	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS76AW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS76AW	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

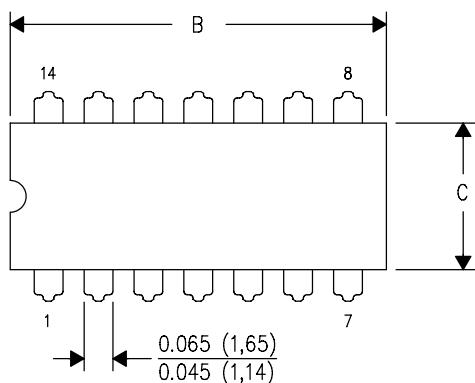
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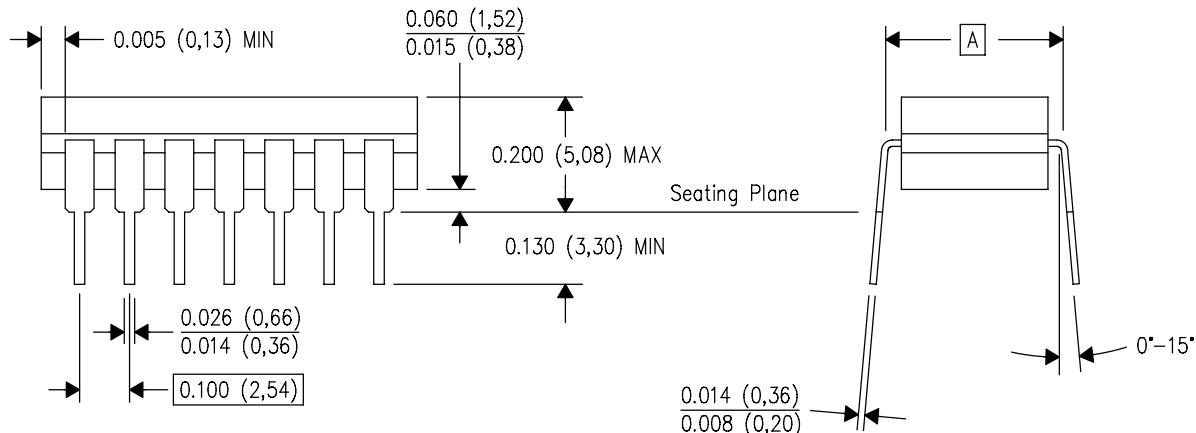
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

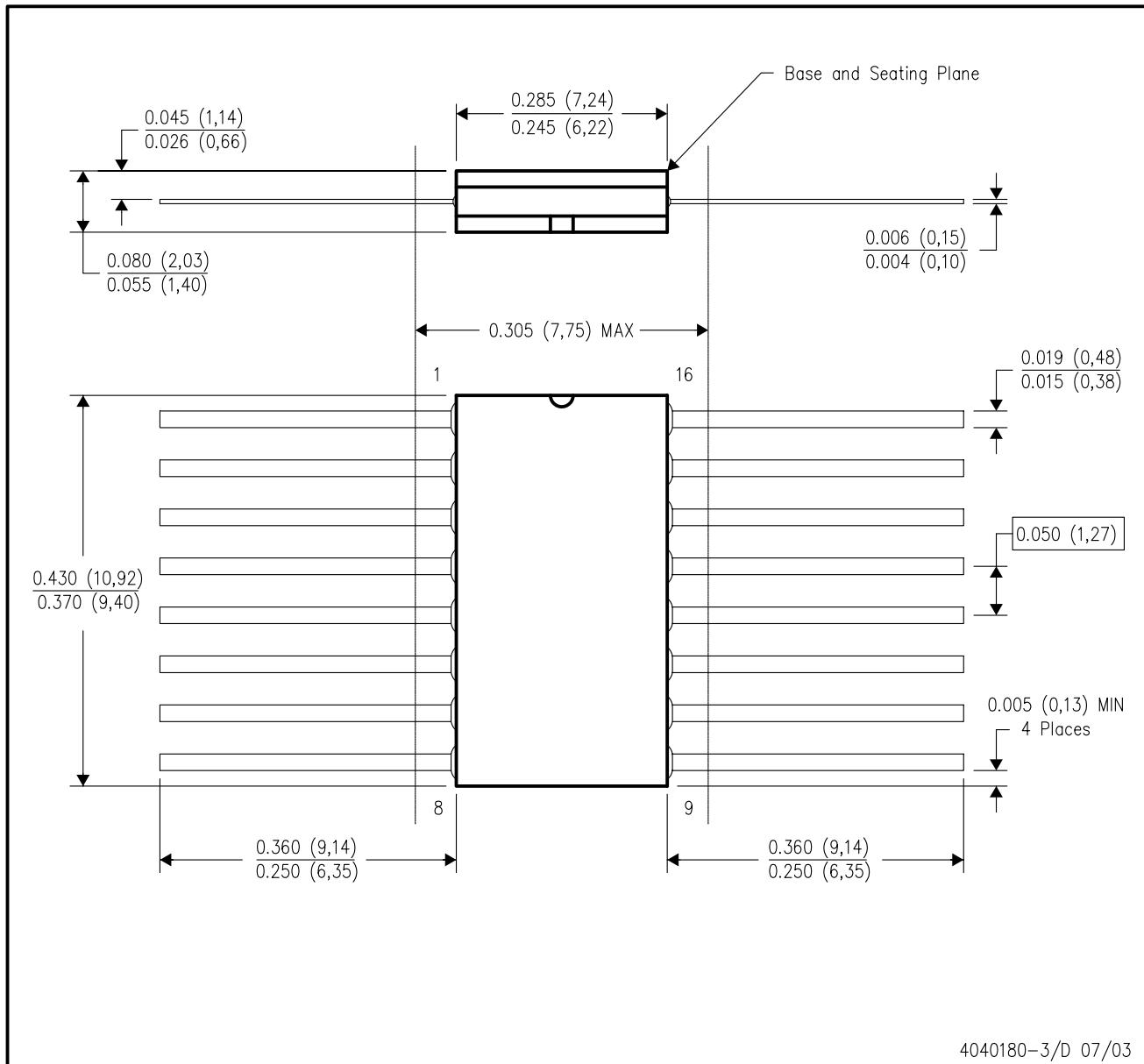


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



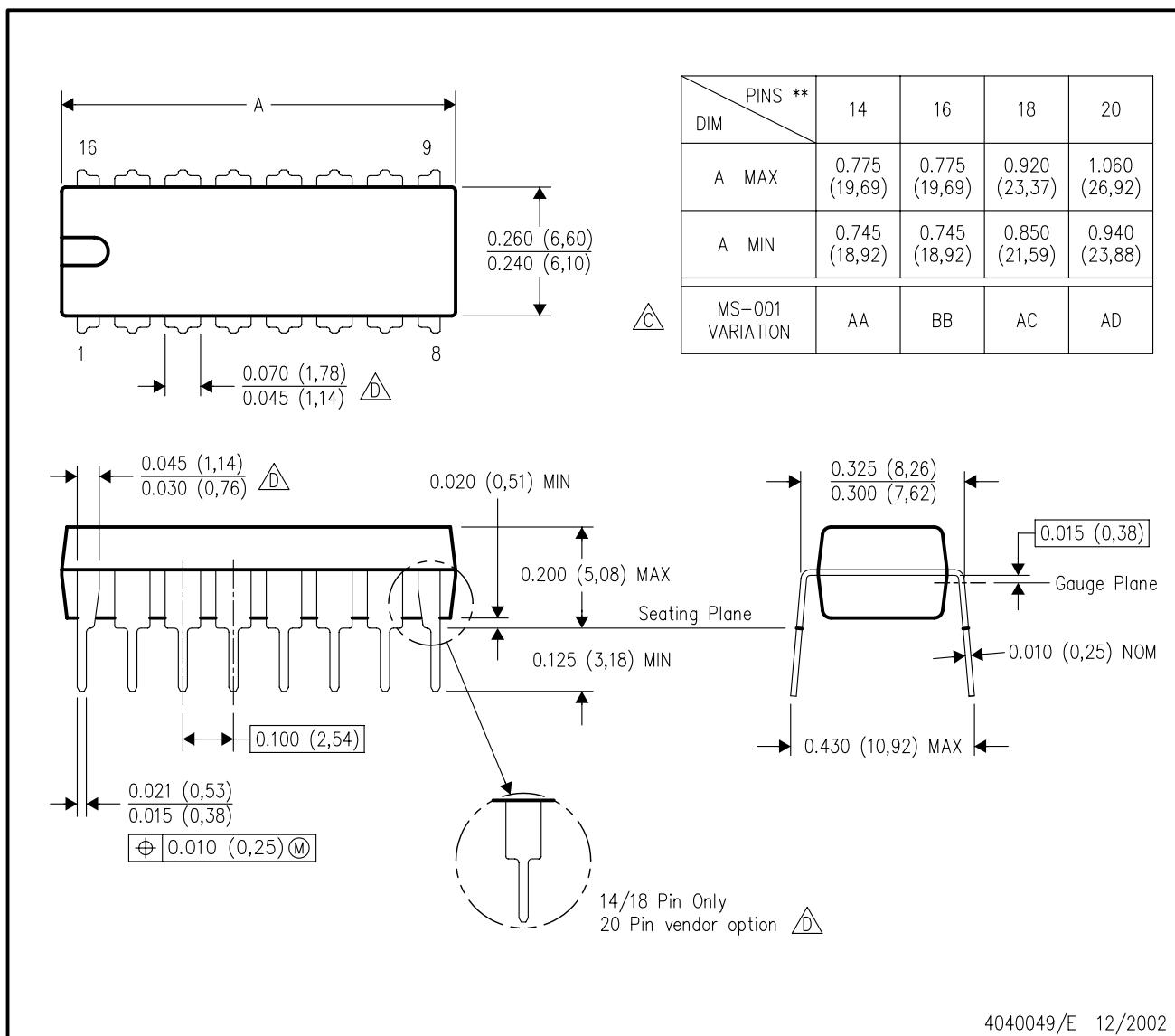
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

N (R-PDIP-T**)

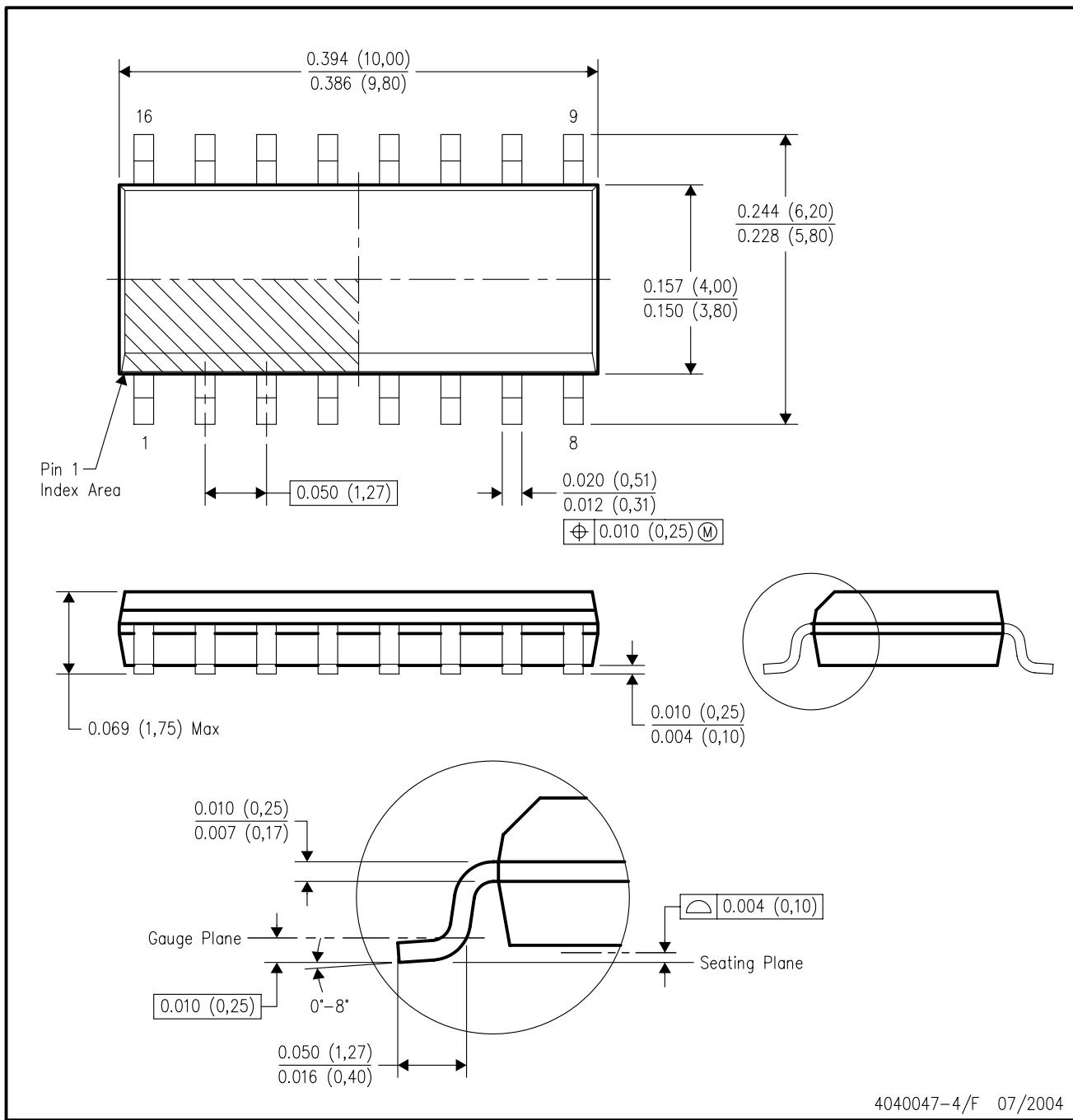
16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/F 07/2004

NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-012 variation AC.

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